

ABSTRACT

The invention concerns a microstructure comprising in a first layer insulated from a substrate (6) by an insulator layer (7) at least one sensitive element (1) connected to at least one contact pad (3) by an electrical connection (2) and protected by a package cap (5). The sensitive element (1), the electrical connection (2) and the contact pad (3) form an assembly (10) delimited in the first layer by at least one trench (11), said assembly (10) being covered by the package cap (5), said package cap (5) comprising at least one opening (12) above the contact pad (3) and being integral on the one hand with the contact pad (3) on the edges of the opening (12) and on the other hand with a zone (9) located beyond the trench (11) in relation to the assembly (10).

Application in particular to
microelectromechanical structures.